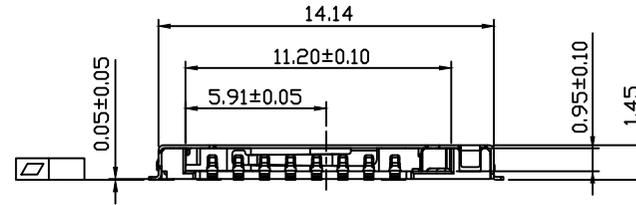
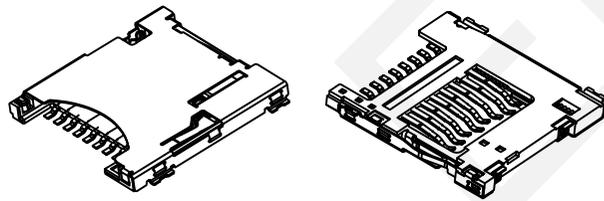
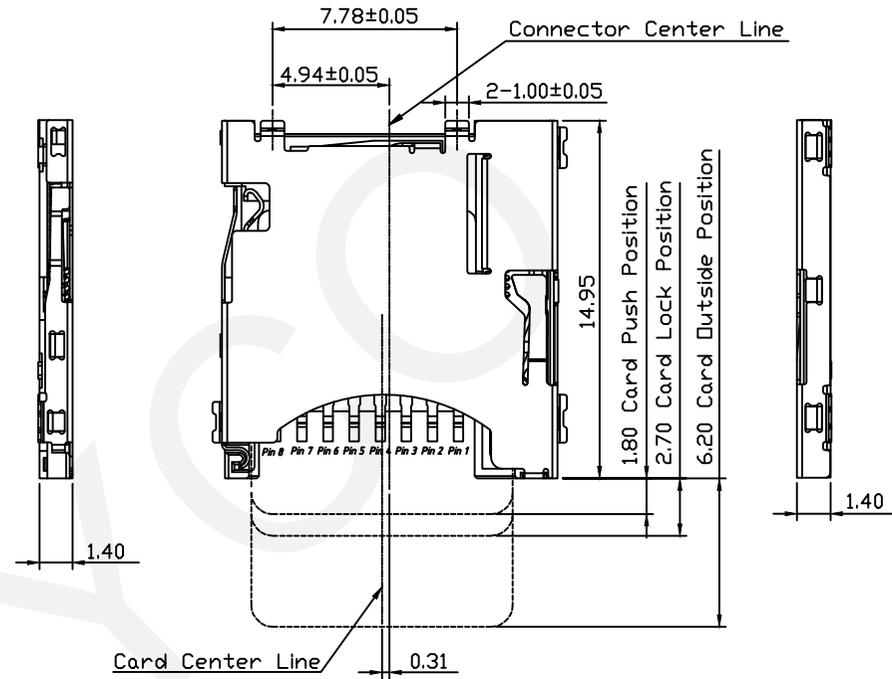
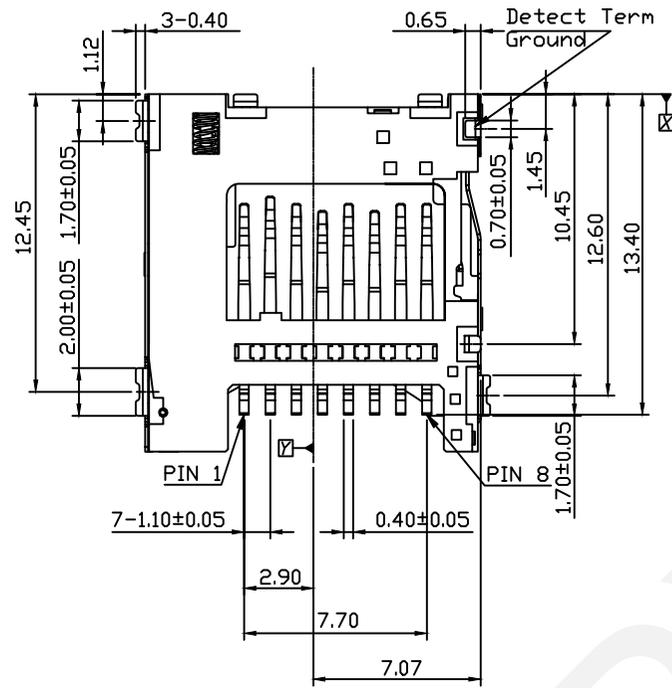


RoHS Compliance



NINGBO ERYCO ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4	SCALE:---	DRWN BY PAN
0~3	3~18	18~50	50~120
±0.12	±0.15	±0.3	±0.5

CHK'D BY FENG  
APPR BY ZHAN

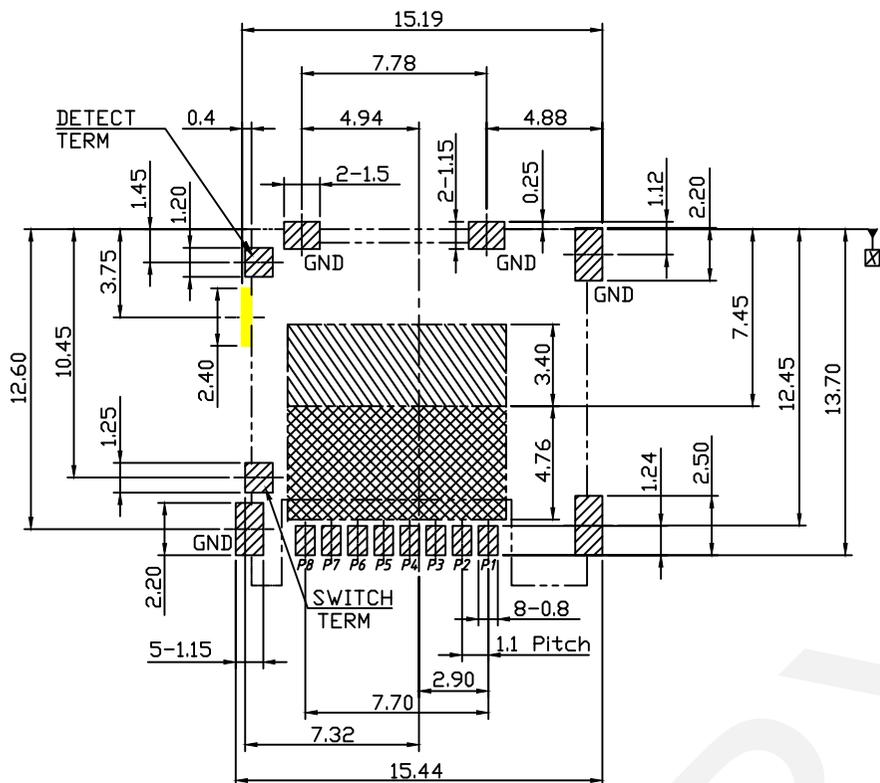
Micro SD Card CONN:PUSH/  
PUSH,H1.4mm,SMD With CD Pin

THIRD ANGLE PROJECTION



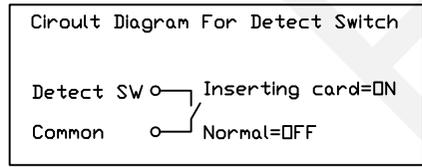
ERYAYF-016

RoHS Compliance



RECOMMENDED PCB LAYOUT  
TOLERANCE UNLESS OTHERWISE IS±0.05

- PROHIBITED AREA
- SOLDER PROHIBITED AREA
- PATTERN PROHIBITED AREA
- PAD AREA



PIN NO.	DISCRIPTION
Pin 1	DAT2:Data Line
Pin 2	CD/DAT3:Card Detect/Dataline
Pin 3	CMD:Command/Pesponse
Pin 4	VDD:Supply Voltage
Pin 5	CLK:Clock
Pin 6	VSS:Supply Voltage Ground
Pin 7	DAT0:Data Line
Pin 8	DAT1:Data Line
GND	Cover GND
Switch Term	Detect SW<CD>
Detect Term	Detect SW<GND>

1. Material :

- 1.1 Insulator:High Temperature Thermoplastic,(LCP,MG350),UL Black 94V-0
- 1.2 Contact:Phosphor Bronze(C5210R-H,T=0.15±0.03mm)
- 1.3 Shell:SUS304-H T=0.12±0.03mm

2.Plating:

- 2.1 Contact: Plated 50u\*Min Ni Overall,Plated 1u\*Min Au Selective Contact Area, Plated 100u\*Min Sn Over Ni On Solder Area.
- 2.2 Shell: Plated 50u\*Min Ni Overall,Plated 1u\*Min Au Selective Contact Area

3.Property:

- 3.1 Current Rating :0.5A AC/DC Max.
- 3.2 Voltage Rating :3.3V/5V(AC/DC)
- 3.3 Contact Resistance:Contact Pin 100mΩ Max.
- 3.4 Insert/Pulling Force: 40N Max/0.5 40N
- 3.5 Smt Solder Temperature: Should Under 260°C
- 3.6 Operation Temperature Range: -40 +85°C

NINGBO ERYCO ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4			SCALE:---	DRWN BY PAN
0~3	3~18	18~50	50~120	CHK'D BY FENG	
±0.12	±0.15	±0.3	±0.5	APPR BY ZHAN	

Micro SD Card CONN:PUSH/ PUSH,H1.4mm,SMD With CD Pin	
THIRD ANGLE PROJECTION	ERYAYF-016